Market News

EiceDRIVER™ X3 Enhanced and X3 Compact: Highly flexible and easy-to-design-in gate driver families now with reinforced isolation

Munich, Germany – 22 April 2021 – Infineon Technologies AG (FSE: IFX / OTCQX: IFNNY) has expanded its easy-to-design EiceDRIVER™ X3 Compact (1ED31xx) and the highly flexible EiceDRIVER X3 Enhanced Analog (1ED34xx) and Digital (1ED38xx) gate driver families. Both families now offer variants with superior reinforced isolation for higher application safety and long operating life. The new family members are VDE 0884-11 certified. With 8 mm wide-body packages, both families are suitable for applications with demanding isolation requirements including industrial drives, solar systems, uninterruptible power supplies, EV charging and other industrial applications.

The versatile EiceDRIVER X3 Compact family provides driving currents of 5.5, 10 and 14 A and optimized propagation delays of 90 ns. The family also includes a Miller clamp that is highly recommended for SiC MOSFET 0 V turn-off. With these features, the 1ED31xx is suitable for high switching frequency applications, IGBT7 and power switches with voltage ratings up to 2300 V.

The EiceDRIVER X3 Enhanced Analog and Digital families offer precise and adjustable DESAT, as well as additional configurable parameters based on I^2C. This supports high flexibility in designs and reduces hardware complexity and evaluation time. Furthermore, the built-in monitoring functionality enables predictive maintenance.

Availability

The EiceDRIVER X3 Enhanced 1ED34xx and 1ED38xx as well as the EiceDRIVER X3 Compact 1ED31xx can be ordered now, as can the evaluation boards EVAL-1ED3121MX12H, EVAL-1ED3122MX12H, EVAL-1ED3124MX12H, EVAL-1ED3491MX12M. More information is available at www.infineon.com/gdisolated. The EiceDRIVER families will be showcased at Infineon's Virtual Power Conference, which complements "PCIM Europe digital days."

For the Trade Press: INFIPC202104.060e

Fabian Schiffer (Headquarters)	Tel.: +49 89 234 25869	fabian.schiffer@infineon.com	**Investor Relations:**
Agnes Toan (Americas)	Tel.: +1 408 250 1814	agnes.toan@infineon.com	Tel: +49 89 234 26655
Chi Kang David Ong (Asia-Pacific)	Tel.: +65 6876 3070	david.ong@infineon.com	investor.relations@infineon.com
Jonas Zhang (Greater China)	Tel.: +86 21 6101 9315	jonas.zhang@infineon.com	
Yoko Sasaki (Japan)	Tel.: +81 3 5745 7340	yoko.sasaki@infineon.com	

Infineon's Virtual Power Conference 2021

Experience the difference in Power – Power semiconductors are the key to an energy-efficient world. New technologies such as silicon carbide (SiC) and gallium nitride (GaN) enable higher power efficiency, smaller form factors and lower weight. Silicon also plays a major role in many designs. Energy efficiency is the focus of the "Virtual Power Conference," which will be available 'live' from May 4 to 6, 2021. As a leading supplier of power semiconductors, Infineon will use the exclusive digital platform to present technologies and systems that generate energy more efficiently, transmit and distribute with lower losses, and showcase a wide range of energy-efficient applications. Focus areas comprise the verticals Industry, Transport & e-Mobility and Consumer. The online platform opens its doors starting 4 May 2021. Please click here to register.

For the Trade Press: INFIPC2021XX.0XXe

Fabian Schiffer (Headquarters)	Tel.: +49 89 234 25869	fabian.schiffer@infineon.com	**Investor Relations:**
Agnes Toan (Americas)	Tel.: +1 408 250 1814	agnes.toan@infineon.com	Tel: +49 89 234 26655
Chi Kang David Ong (Asia-Pacific)	Tel.: +65 6876 3070	david.ong@infineon.com	investor.relations@infineon.com
Jonathan Liu (Greater China)	Tel.: +86 21 6101 9182	jonathan.liu@infineon.com	
Yoko Sasaki (Japan)	Tel.: +81 3 5745 7340	yoko.sasaki@infineon.com	